



PATENT  
0763-0173P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant:	Dong Kyun SOHN et al.	Conf.:	9674
Appl. No.:	10/620,608	Group:	2814
Filed:	July 17, 2003	Examiner:	L. PHAM
For:	METHOD OF FORMING FILM FOR REDUCED OHMIC CONTACT RESISTANCE AND TERNARY PHASE LAYER AMORPHOUS DIFFUSION BARRIER (To be Amended)		

LARGE ENTITY TRANSMITTAL FORM

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

June 3, 2004

Sir:

Transmitted herewith is an amendment in the above-identified application.

- ☐ The enclosed document is being transmitted via the Certificate of Mailing provisions of 37 C.F.R. § 1.8.
- ☐ The enclosed document is being transmitted via facsimile.

The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR		PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL	5	-	20	=	0	\$ 18	\$0.00
INDEPENDENT	2	-	3	=	0	\$ 86	\$0.00
<input type="checkbox"/> FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM						\$290	\$0.00
						TOTAL	\$0.00

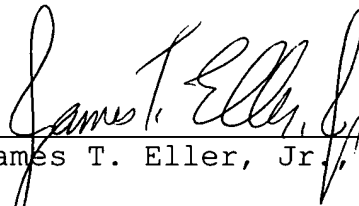
- ☐ Petition for ( ) month(s) extension of time pursuant to 37 C.F.R. §§ 1.17 and 1.136(a). \$0.00 for the extension of time.
- ☒ No fee is required.
- ☐ Check(s) in the amount of \$0.00 is(are) enclosed.
- ☐ Please charge Deposit Account No. 02-2448 in the amount of \$0.00. This form is submitted in triplicate.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17; particularly, extension of time fees.

Respectfully submitted,

BIRCH, STEWART, KOLASCH & BIRCH, LLP

By



James T. Eller, Jr., #39,538

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Attachment(s)

(Rev. 02/08/2004)



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For: METHOD OF FORMING FILM FOR REDUCED OHMIC  
CONTACT RESISTANCE AND TERNARY PHASE  
LAYER AMORPHOUS DIFFUSION BARRIER (To be  
Amended)

AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

June 3, 2004

Sir:

In response to the Examiner's Office Action dated March 3, 2004,  
the following amendments and remarks are respectfully submitted in  
connection with the above-identified application.

*Amendments to the Title of the Invention*

Please change the Title of the Invention to --SEMICONDUCTOR  
DEVICE INCLUDING TERNARY PHASE DIFFUSION BARRIER--.